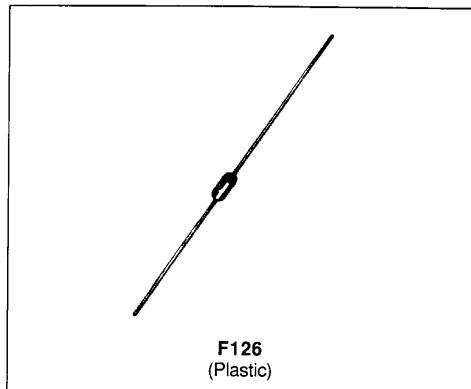


UNIDIRECTIONAL TRANSIENT VOLTAGE SUPPRESSOR



DESCRIPTION

Transient voltage suppressor diode especially designed for transistor protection in electronic ignition circuit.

Connected across collector and base it avoids any transistor damage when spark plug is fouled or disconnected.

ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit
P _{tot}	DC Power Dissipation	1.7	W
I _{ZM}	Continuous Reverse Current	3.5	mA
P _{RSM}	Non Repetitive Surge Peak Power Dissipation	300	W
T _{oper}	Operating Temperature	– 55 to 150	°C
T _{stg} T _j	Storage and Junction Temperature Range	– 55 to 150 150	°C °C
T _L	Maximum Lead Temperature for Soldering During 3 s at 5 mm from Case	300	°C

THERMAL RESISTANCE

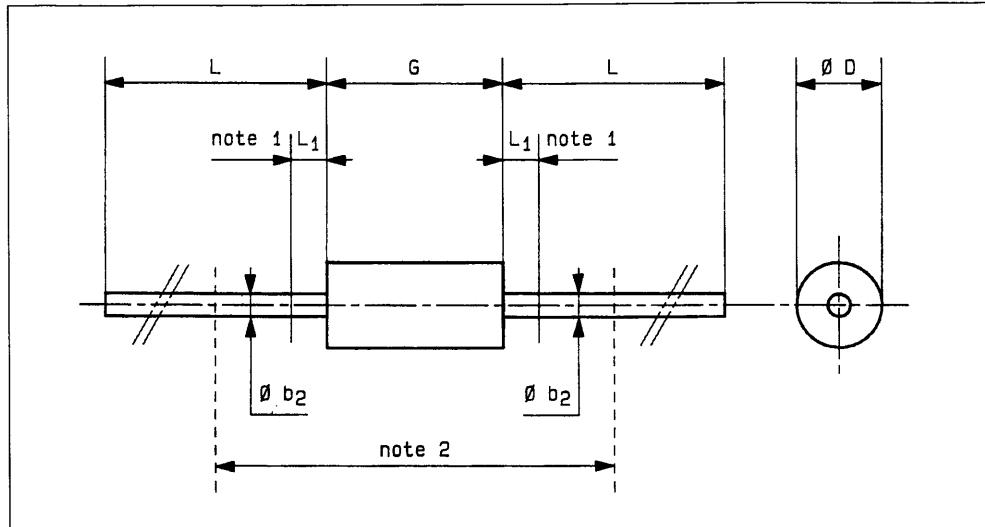
Symbol	Parameter	Value	Unit
R _{th(j-l)}	Junction-leads on Infinite Heatsink for L _{lead} = 10 mm	60	°C/W

ELECTRICAL CHARACTERISTICS

Type	V_{BR} @ $T_j = 25^\circ C$ min. max.	V_{BR} @ $T_j = 120^\circ C$ min. max.	I_R	α_T typ.	I_{RM}/V_{RM} max.	V_{RM}	I_{ZM}
	(V)	(V)	(mA)	($10^{-4}/^\circ C$)	(μA)	(V)	(mA)
PL 360 D	330 - 370	358 - 416	2	11	0.35	270	3.5

PACKAGE MECHANICAL

F 126 Plastic



Ref.	Millimeters		Inches		Notes
	Min.	Max.	Min.	Max.	
$\emptyset b_2$	0.76	0.86	0.029	0.034	
$\emptyset D$	2.95	3.05	0.116	0.120	
G	6.05	6.35	0.238	0.250	1 - The lead diameter $\emptyset b_2$ is not controlled over zone L ₁ .
L	26	-	1.024	-	2 - The minimum axial length within which the device may be placed with its leads bent at right angles is 0.59" (15 mm).
L ₁	-	1.27	-	0.050	

Cooling method : by convection (method A).

Marking : type number ; white band indicates cathode.

Weight : 0.4 g.

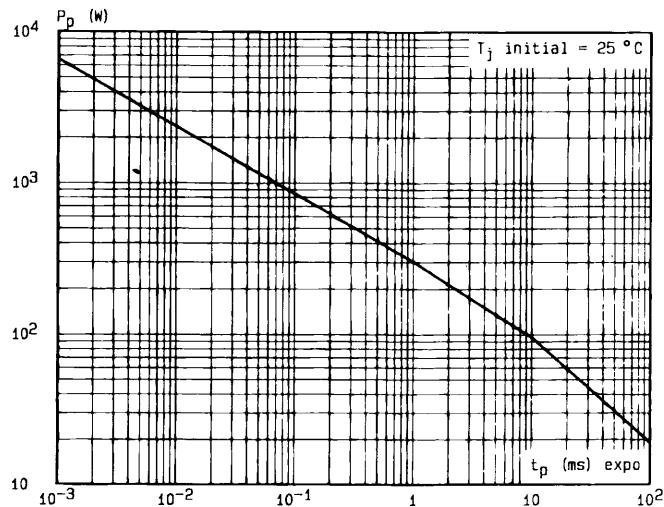
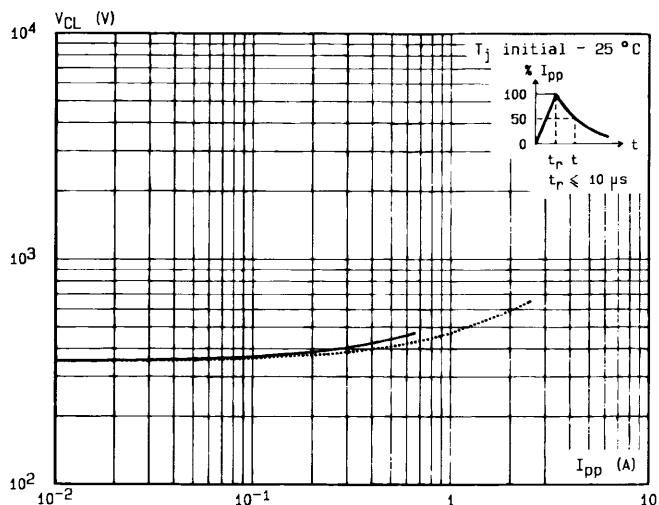


Fig.1 - Peak pulse power versus exponential pulse duration.

Fig.2 - Clamping voltage versus peak pulse current
exponential waveform $t = 20 \mu\text{s}$
 $t = 1 \text{ ms}$ —

Note : The curves of the figure 2 are specified for a junction temperature of 25°C before surge. The given results may be extrapolated for other junction temperatures by using the following formula : $\Delta V_{(BR)} = \alpha_{T_j} (V_{(BR)}) \times [T_j - 25] \times V_{(BR)}$
For intermediate voltages, extrapolate the given results.

DB9PL360DP3

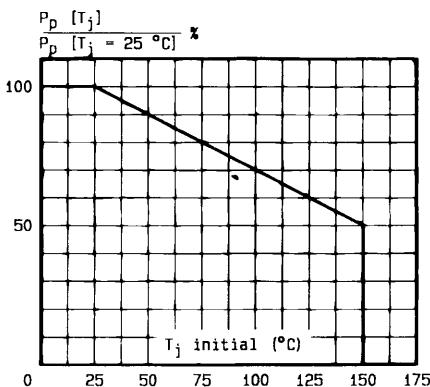


Fig.3 - Allowable power dissipation versus junction temperature.

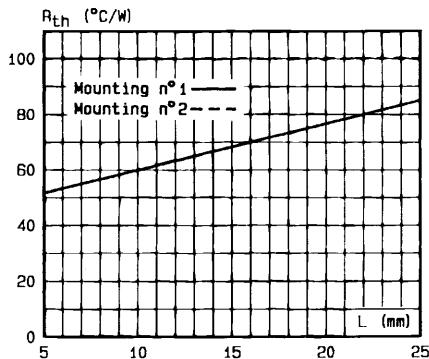


Fig.5 - Thermal resistance versus lead length.

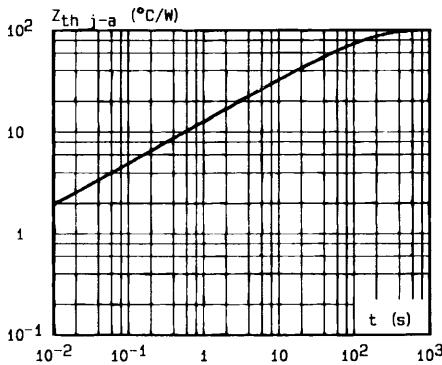


Fig.6 - Transient thermal impedance junction-ambient for mounting n°2 versus pulse duration ($L = 10$ mm).

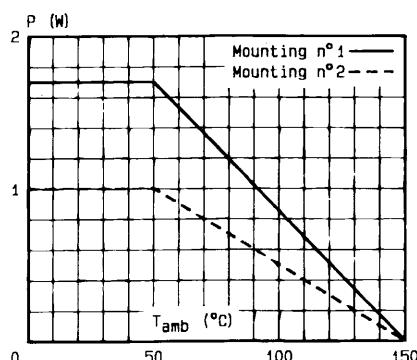


Fig.4 - Power dissipation versus ambient temperature.

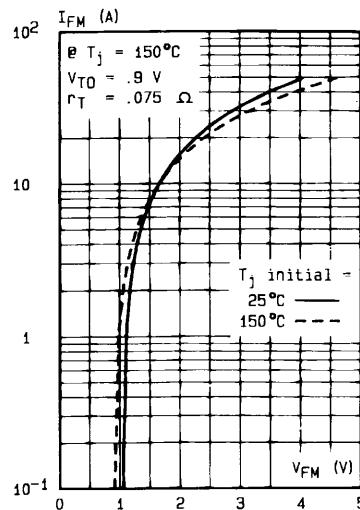
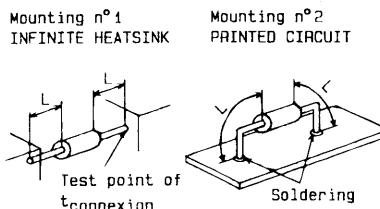


Fig.7 - Peak forward current versus peak forward voltage drop (typical values for unidirectional types).

DB9PL360DP4

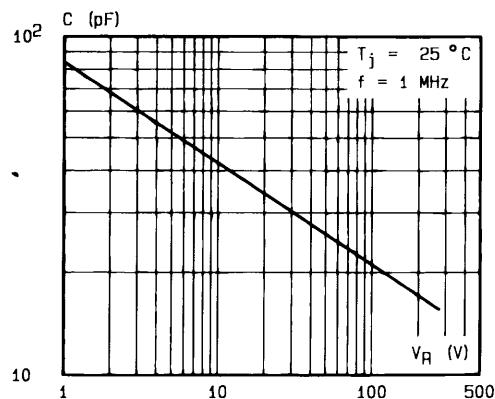
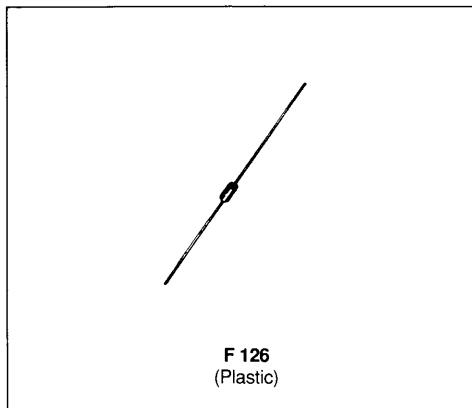


Fig.8 - Capacitance versus reverse applied voltage (typical values).

D89PL360DP5

REFERENCE DIODE



DESCRIPTION

Very low voltage reference diodes in plastic package for specific applications where very tight ΔV_z is required. ΔV_z lower than 100mV for a forward current of 5mA.

ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit
$I_{F(AV)}$	Average Forward Current*	0.4	A
I_{FSM}	Surge non Repetitive Forward Current	30	A
T_{stg} T_j	Storage and Junction Temperature Range	- 55 to 125	°C
T_L	Maximum Lead Temperature for Soldering during 10s at 4mm from Case	230	°C

THERMAL RESISTANCE

Symbol	Parameter	Value	Unit
$R_{th} (j-a)$	Junction-ambient**	100	°C/W

* Single phase, half wave, resistive or inductive load, L (leads) = 10mm.

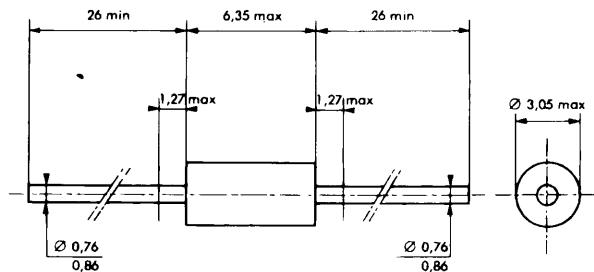
** On printed circuit with L = 10mm.

ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Conditions	min.	Typ.	Max.	Unit
I_R	$T_j = 25^\circ C$	$V_R = 5V$			10	µA
V_F	$T_j = 25^\circ C$	$I_F = 5mA$	0.65		0.75	V
R	$T_j = 25^\circ C$	$I_F = 5mA$			10	Ω
αV_F	$25^\circ C \leq T_j \leq 125^\circ C$	$I_F = 5mA$	- 25		- 30	$10^{-4}/^\circ C$

PACKAGE MECHANICAL DATA

F 126 (Plastic)



Cooling method : by convection (method A).

Marking : clear, ring at cathode end.

Weight : 0.4g

REFERENCE DIODE



F 126
(Plastic)

DESCRIPTION

Low voltage reference diodes in plastic package for specific applications where very tight ΔV_z is required. ΔV_z specified is lower than 150mV for a forward current of 5mA.

ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit
$I_{F(AV)}$	Average Forward Current*	0.4	A
I_{FSM}	Surge non Repetitive Forward Current	30	A
T_{stg} T_j	Storage and Junction Temperature Range	- 55 to 125	°C
T_L	Maximum Lead Temperature for Soldering during 10s at 4mm from Case	230	°C

THERMAL RESISTANCE

Symbol	Parameter	Value	Unit
$R_{th (J-a)}$	Junction-ambient**	100	°C/W

* Single phase, half wave, resistive or inductive load, L (leads) = 10mm.

** On printed circuit with L = 10mm.

ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Conditions	min.	Typ.	Max.	Unit
I_R	$T_j = 25^\circ C$	$V_R = 5V$			10	μA
V_F	$T_j = 25^\circ C$	$I_F = 5mA$	1.35		1.55	V
R	$T_j = 25^\circ C$	$I_F = 5mA$			20	Ω
αV_F	$25^\circ C \leq T_j \leq 125^\circ C$	$I_F = 5mA$	- 25		- 30	$10^{-4}/^\circ C$